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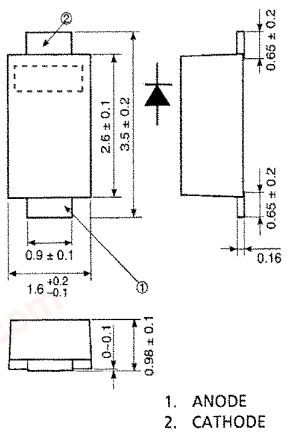
TOSHIBA Schottky Barrier Rectifier Schottky Barrier Type

CRS09

Switching Mode Power Supply Applications
Portable Equipment Battery Applications

- Forward voltage: V_{FM} = 0.46 V (max)
- Average forward current: $I_{F\ (AV)}$ = 1.5 A
- Repetitive peak reverse voltage: V_{RRM} = 30 V
- Suitable for compact assembly due to small surface-mount package "S−FLAT™" (Toshiba package name)

Unit: mm



JEDEC	—
JEITA	—
TOSHIBA	3-2A1A

Weight: 0.013 g (typ.)

Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit
Repetitive peak reverse voltage	V_{RRM}	30	V
Average forward current	$I_{F\ (AV)}$	1.5 (Note)	A
Peak one cycle surge forward current (non-repetitive)	I_{FSM}	30 (50 Hz)	A
Junction temperature	T_j	−40~150	°C
Storage temperature	T_{stg}	−40~150	°C

Note: Ta = 84°C
Device mounted on a ceramic board
(board size: 50 mm × 50 mm, land size: 2 mm × 2 mm)

Electrical Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Peak forward voltage	$V_{FM\ (1)}$	I_{FM} = 0.1 A	—	0.35	—	V
	$V_{FM\ (2)}$	I_{FM} = 1.0 A	—	0.415	—	
	$V_{FM\ (3)}$	I_{FM} = 1.5 A	—	0.43	0.46	
Repetitive peak reverse current	$I_{RRM\ (1)}$	V_{RRM} = 5 V	—	0.8	—	μA
	$I_{RRM\ (2)}$	V_{RRM} = 30 V	—	10	50	
Junction capacitance	C_j	V_R = 10 V, f = 1.0 MHz	—	90	—	pF
Thermal resistance (junction to ambient)	$R_{th\ (j\text{-}a)}$	Device mounted on a ceramic board (soldering land: 2 mm × 2 mm)	—	—	70	°C/W
		Device mounted on a glass-epoxy board (soldering land: 6 mm × 6 mm)	—	—	140	
Thermal resistance (junction to lead)	$R_{th\ (j\text{-}\ell)}$	—	—	—	20	°C/W

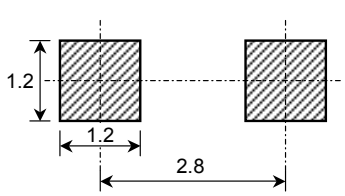
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Marking

Abbreviation Code	Part No.
S9	CRS09

Standard Soldering Pad

Unit: mm



Handling Precaution

Schottky barrier diodes have reverse current characteristics compared to other diodes.
There is a possibility SBD may cause thermal runaway when it is used under high temperature or high voltage.
Please take forward and reverse loss into consideration during design.

The maximum ratings denote the absolute maximum ratings, which are rated values and must not be exceeded during operation, even for an instant. The following are the general derating methods that we recommend when you design a circuit with a device.

V_{RRM}: Use this rating with reference to the above. V_{RRM} has a temperature coefficient of 0.1%/°C. Take this temperature coefficient into account designing a device at low temperature.

$I_{F(AV)}$: We recommend that the worst case current be no greater than 80% of the maximum rating of $I_{F(AV)}$ and T_j be below 120°C. When using this device, take the margin into consideration by using an allowable Tamax-$I_{F(AV)}$ curve.

I_{FSM}: This rating specifies the non-repetitive peak current. This is only applied for an abnormal operation, which seldom occurs during the lifespan of the device.

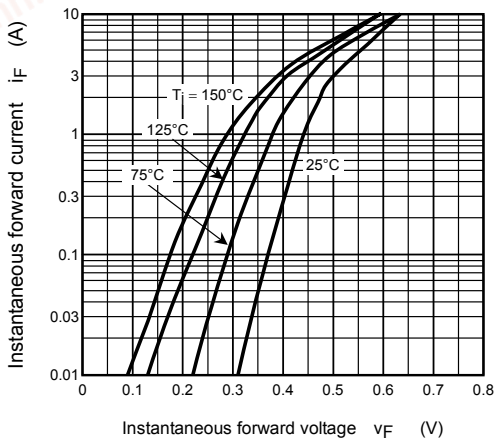
T_j: Derate this rating when using a device in order to ensure high reliability. We recommend that the device be used at a T_j of below 120°C.

Thermal resistance between junction and ambient fluctuates depending on the device's mounting condition. When using a device, design a circuit board and a soldering land size to match the appropriate thermal resistance value.

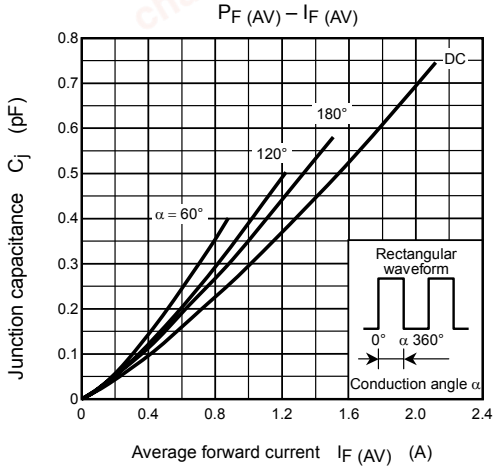
Please refer to the Rectifiers databook for further information.

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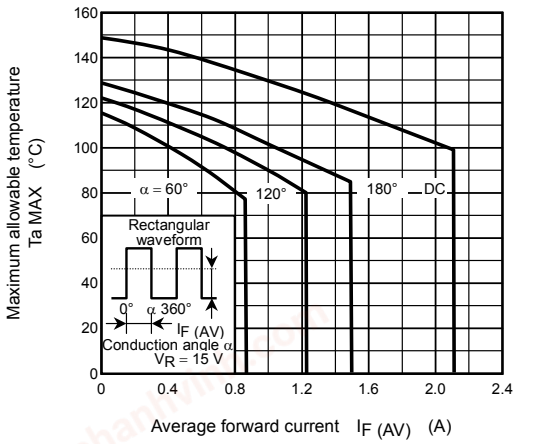
$i_F - v_F$



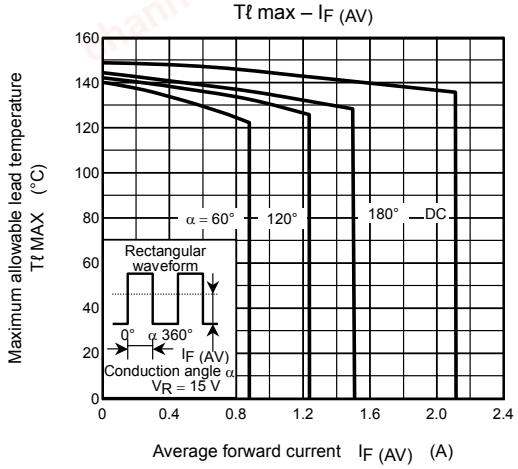
$P_{F\ (AV)} - I_{F\ (AV)}$



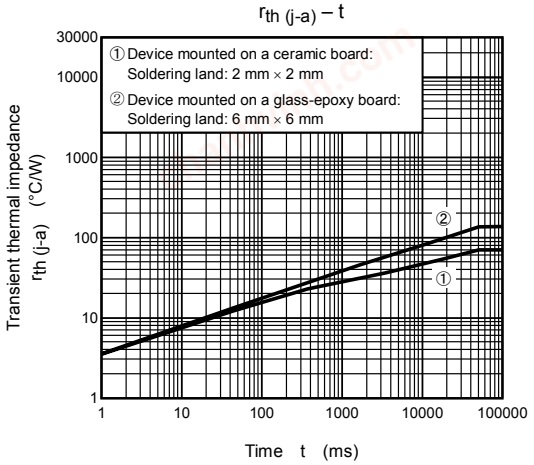
Ta MAX – $I_{F\ (AV)}$
Ceramic substrate (substrate size 50 mm × 50 mm)



$T\ell$ max – $I_{F\ (AV)}$

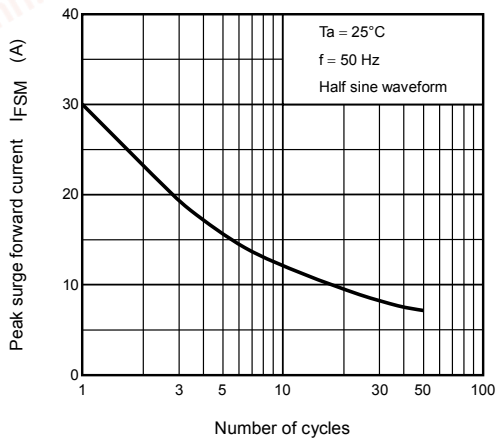


$r_{th\ (j\text{-}a)} - t$

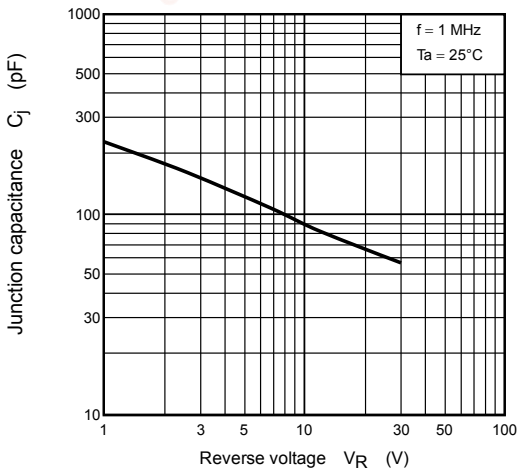


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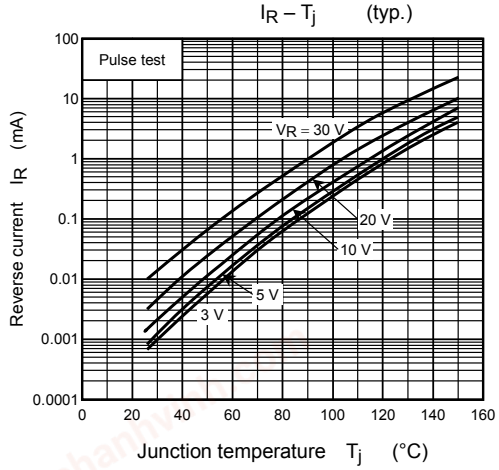
Surge forward current
(non-repetitive)



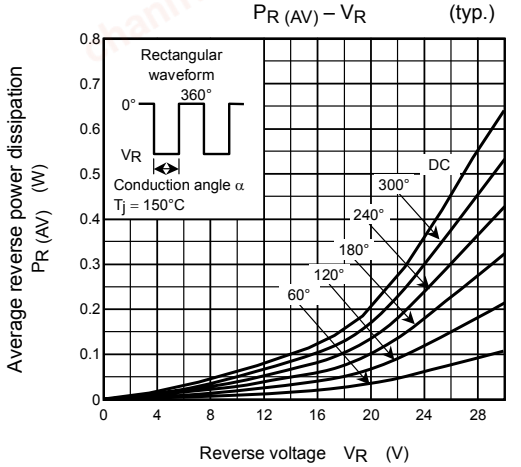
$C_j - V_R$ (typ.)



$I_R - T_j$ (typ.)



$P_{R\,(AV)} - V_R$ (typ.)



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